PCN Number:		201	6020)202002		PCN D	ate:	02/05/2016	
Title:	Title: Qualification of RFAB for Select LBC8 Devices								
Customer Contact:			PCN Manager Der			Dept	t: Quality Services		ity Services
Proposed 1 st Ship Date		: 0	05/05/2016 Estimated Sample Availability:			Date provided at sample request.			
Change									
Assembly Site				Assembly Process		Ass	Assembly Materials		
Des	sign			Electrical Specification		Med	Mechanical Specification		
Tes	t Site			Packing/Shipping/Labeling		Test	Test Process		
Wafer Bump Site				Wafer Bump Material		Waf	Wafer Bump Process		
				Wafer Fab Materials		Waf	Wafer Fab Process		
				Part number change			`		
PCN Details									

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional wafer FAB source for the selected devices listed in "Product Affected" section.

	Current Sites		Additional Sites		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DP1DM5	LBC8	200 mm	RFAB	LBC8	300 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Changes to product identification resulting from this PCN:

Chip Site Origin Code

Current

RFAB RFB		USA	Richardson
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
New			
DP1DM5	DP1DM5 DM5		Richardson
Chip Sites	Chip Sites (20L)		Chip Site City

Chip Site Country

Sample product shipping label (not actual product label)







Product Affected:						
DRV83053PHP	DRV83055PHPR	SN1505019PHPR				
DRV83053PHPR	DRV8305NPHP	SNC2025PHPR				
DRV83055PHP	DRV8305NPHPR					

QUALIFICATION DATA

Hayate (SNC2025PHPR) RFAB Offload Approve Date 29-Jan-2016

Attributes	Qual Device: SNC2025PHPR	QBS Product Reference: SNC2024PHP	QBS Process Reference: SN96019PFP
Assembly Site	TIPI	PHI (TIPI)	PHI (TIPI)
Package Family	TQFP	TQFP	HTQFP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	DM5	RFAB
Wafer Process	LBC8	LBC8	LBC8

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: SNC2025PHPR	QBS Product Reference: SNC2024PHP	QBS Process Reference: SN96019PFP
AC	Autoclave 121C	96 Hours	-	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	1/30/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
НВМ	ESD - HBM	4000 V	-	1/3/0	-
CDM	ESD - CDM	1500 V	-	-	3/9/0
HTOL	Life Test, 125C	1000 Hours	-	1/77/0	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0
LI	Lead Fatigue	Leads	-	-	-
LI	Lead Pull to Destruction	Leads	-	-	-
LU	Latch-up	(per JESD78)	-	2/12/0	1/6/0
PD	Physical Dimensions		-	-	-
SD	Surface Mount Solderability	Pb Free	-	-	-
TC	Temperature Cycle, - 65/150C	500 Cycles	-	1/77/0	3/231/0
TS	Thermal Shock, - 65/150C	500 Cycles	-	-	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-
WBP	Bond Pull	Wires	-	-	-
WBS	Ball Bond Shear	Wires	-	-	-

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7 eV: 150 C/1 k Hours, and 170 C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report DRV8305 RFAB Offload Approve Date 25-Jan-2016

Attributes	Qual Device: DRV83053PHPR	Qual Device: DRV83055PHPR	Qual Device: DRV8305NPHPR	QBS Product Reference: DRV8305PHP	QBS Process Reference: SN96019PFP
Assembly Site	TITL	TITL	TITL	TAI / TITL	PHI (TIPI)
Package Family	HTQFP	HTQFP	HTQFP	HTQFP	HTQFP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	RFAB	RFAB	DM5	RFAB
Wafer Process	LBC8	LBC8	LBC8	LBC8	LBC8

QBS: Qual By Similarity

⁻ Qual Devices qualified at LEVEL3-260CG: DRV83053PHPR, DRV8305NPHPR, DRV83055PHPR

Туре	Test Name / Condition	Duration	Qual Device: DRV83053PHPR	Qual Device: DRV83055PHPR	Qual Device: DRV8305NPHPR	QBS Product Reference: DRV8305PHP	QBS Process Reference: SN96019PFP
AC	Autoclave 121C	96 Hours	=	-	=	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0
HBM	ESD - HBM	4000 V	=	=	=	1/3/0	-
CDM	ESD - CDM	1500 V	-	=	-	-	3/9/0
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-	3/231/0
LU	Latch-up	(per JESD78)	-	-	-	2/12/0	1/6/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	1/77/0	3/231/0
WBP	Bond Pull	Wires	-	-	-	-	-
WBS	Ball Bond Shear	Wires	-	-	-	-	-
YLD	FTY and Bin Summary		-	1/Pass	1/Pass	-	-

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

⁻ The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7 eV: 150 C/1 k Hours, and 170 C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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